

HIGHLIGHT

Fully-Automatic Vacuum Wafer Mounter

RAD-2512F/12



-  High-precision vacuum mounting
-  Non-contact wafer handling
-  Advanced inline pre-cut system
-  Wide variety of optional functions
-  Ideal for TAIKO[®] and MEMS



LINTEC Corporation

BENEFITS



High-precision vacuum mounting

Achieves precise mounting of uniquely shaped wafers.



Non-contact wafer handling

Prevents contact with sensitive surfaces or metalizations and is ideally suited for TAIKO® or MEMS wafers.



Advanced inline pre-cut system

Minimizes waste of material, decreases production cost and reduces tape pitch from 10mm to 2mm.

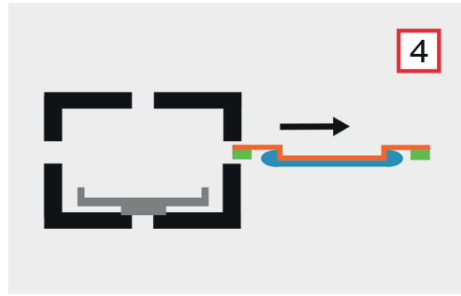
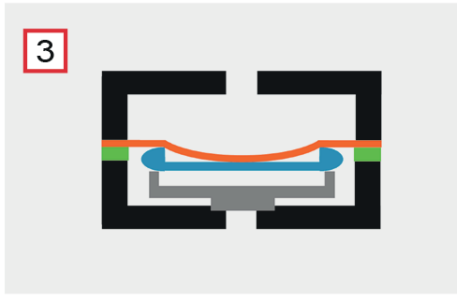
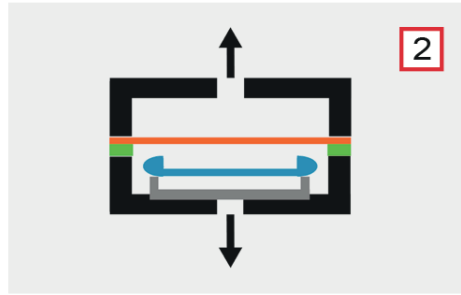
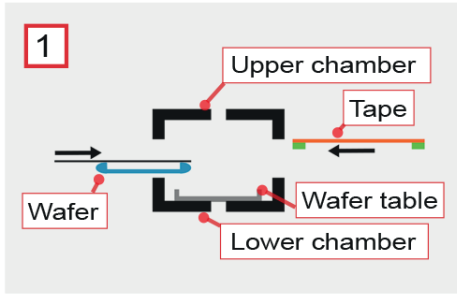


Wide variety of optional functions

RAD-2512F/12 can be equipped with various optional functions, for example wafer-ID reading or OHT-capability.



VACUUM MOUNTING MECHANISM



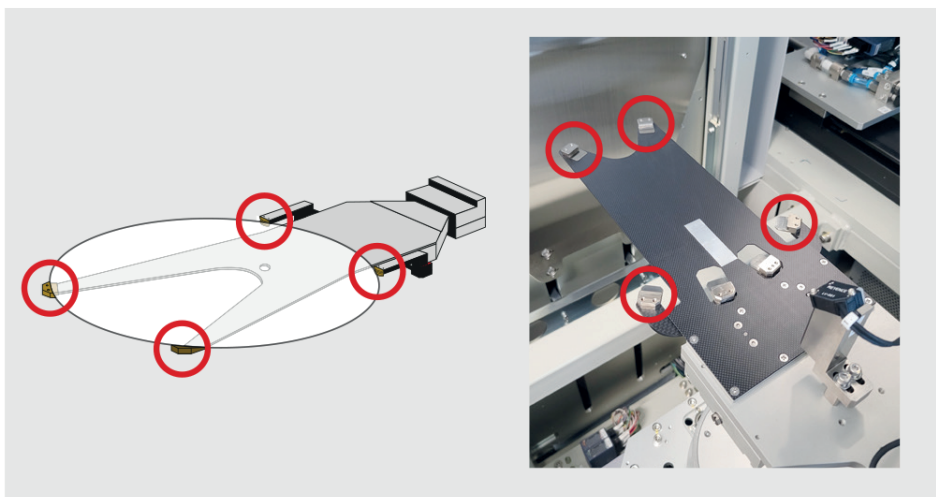
1 The wafer is placed in the lower chamber face-down, the frame with tape in the upper chamber.

2 The vacuum chamber is closed and vacuum generation is initiated.

3 3.1 The tape is mounted under vacuum by applying differential pressure.
3.2 Venting of vacuum chamber to atmosphere.

4 The finished workpiece is handled out of the chamber and further processed through the system.

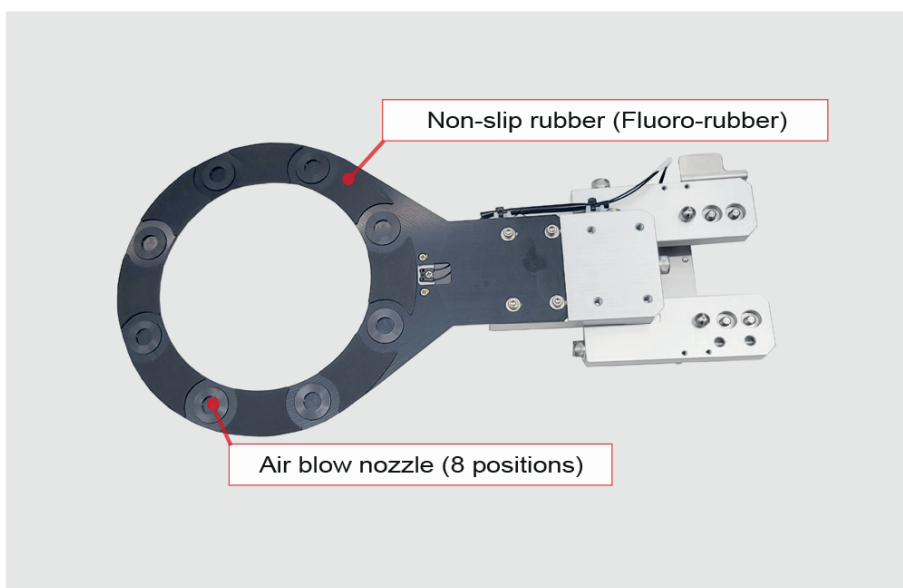
NON-CONTACT HANDLING



Non-contact handling

Prevents damage to sensitive wafer front- or backsides and is therefore ideally suited for handling of TAIKO® or MEMS wafers, as well as for handling of any wafer with sensitive structures.

BERNOULLI HANDLING



Bernoulli wafer handling system

LINTEC's customized robot end-effector is able to process even warped wafers and accommodates for touchless handling of sensitive TAIKO® or MEMS surfaces by applying a Bernoulli soft contact handling approach.

SPECIFICATIONS

Wafer size 200mm

Optional:
300mm, 150mm

Weight 2,600kg

Equipment size 2,203mm (W) x 3,092mm (D) x 1,800mm (H)

UPH 40 wafers/hour (ø200)



STANDARD

- Handling of 200mm wafers
- Non-contact wafer edge-clamp handling system
- Non-contact wafer aligner
- Non-contact vacuum mounting unit
- Post process tape heating function for increased mounting quality
- Single loader and unloader specification
- Anti-ESD specification:
 $\pm 100\text{V}$ or less within 10sec after the end of operation



OPTIONS

- Handling of 150mm or 300mm wafers
- Inline pre-cut unit
- Warped wafer support system
- Camera alignment system
- Wafer-ID reading function
- Double loader and unloader specification
- Host communication function (SECS/GEM)
- OHT capability
- High-class ESD countermeasure specification:
 $\pm 50\text{V}$ or less immediately after the end of operation*

*Reference value, measured on mirror wafer



Adwill

Tape x Equipment

Contact us.
We look forward
to meeting you!



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